

Wafer Level Packaging Market by Integration Type (Fan-in WLP, Fan-out WLP), Packaging Technology (3D IC WLP, 2.5D IC WLP, 2D IC WLP, Nano WLP), Bumping Technology (Copper Pillar, Solder Bumping, Gold Bumping), Industry (Electronics, IT & Telecommunication, Industrial, Automotive) - Global Opportunity Analysis and Industry Forecast, 2014 - 2022

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Abstracts

Wafer level packaging (WLP) is a technology of packaging an integrated circuit where most or all of the packaging process steps are carried out at the wafer level in contrast to the conventional chip scale packaging and wire bonding. The advancements in wafer level packaging deliver highly efficient and reliable electrical interconnect solutions for electronic products. The market holds a great potential in electronics and IT & telecommunication industries. The leading electronic companies like Samsung, Intel and Apple incorporate these packages in their products. For instance, Apple is going to incorporate wafer level fan-out package for their next generation-iPhone 7. Therefore, the increased adoption of advance packaging technology in portable electronics is expected to propel the demand of wafer level packaging in the years to come.

Roadmap for advancements in packaging technology

Wafer level packaging is a cost-effective technology with technological improvements such as lower form factor, smaller thickness, lower pitches, high density of I/O counts, lower power consumption, and higher package density, which makes it an excellent packaging technology for high end electronic gadgets. It is extensively used in portable electronic devices as it enhances the performance and durability of the device, for instance, iPhone 5 has at least 11 different WLPs, the Samsung Galaxy S3 has 6 WLPs

and the HTC One X has 7. Continuous research & development activities to develop innovative and improved packaging technology, are in progress which will lead to the growth of the market.

The growing demand of wafer level packaging technology in industries such as electronics, IT & telecommunication and automotive among others would help in the growth of the wafer level packaging market. WLP enables high functionality with least cost when dealing with complex integrated circuits (IC) with a high number of input/output connections to the outside world. However, strong transmission of mechanical stress between package & board as compared to other package technologies and difficulty in repair due to restricted visual inspection hinders the growth of the market.

Wafer level packaging market is driven by trending Internet of Things (IoT), technological superiority over traditional packaging techniques and impending need of circuit miniaturization in microelectronic devices. In addition, encapsulation being a challenge for fan-out wafer level packaging and high initial investment, functions as key constraints to the market.

The market is segmented on the basis of integration type, packaging technology, bumping technology, industry vertical, and geography. Based on integration type, it is divided into fan-in WLP and fan-out WLP. The market by packaging technology comprises 3D TSV WLP, 2.5D TSV WLP, WLCSP, Nano WLP and others. Based on bumping technology, it is segmented into copper pillar, solder bumping, gold bumping, and others. The market by industry vertical comprises of electronics, IT & telecommunication, industrial, automotive, aerospace & defense, healthcare, and others. Further, the market is analyzed on the basis of regions such as North America, Europe, Asia-Pacific, and LAMEA.

Key players profiled in this report are Amkor Technology Inc., Fujitsu Ltd., Jiangsu Changjiang Electronics Technology Co. Ltd., Deca Technologies, Qualcomm Inc., Toshiba Corp., Tokyo Electron Ltd., Applied Materials, Inc., ASML Holding NV, and Lam Research Corp. among others.

POTENTIAL BENEFITS FOR STAKEHOLDERS:

This report provides an in-depth analysis of the world wafer level packaging market and offers current and future trends to identify lucrative investment pockets

This report identifies the key drivers, opportunities, and restraints that shape the market and provides an impact analysis for the forecast period

Porter's Five Forces analysis highlights the potency of buyers and suppliers that participate in this market. This would further offer a competitive advantage to stakeholders to make profitable business decisions; thereby, helping them to strengthen their supplier and buyer networks

Current and future trends are outlined to determine the overall attractiveness and highlight the profitable trends to gain a stronger foothold

Market estimation of geographic segments is derived from the current scenario and expected trends

MARKET SEGMENTATION

The market is segmented on the basis of integration type, packaging technology, bumping technology, industry vertical, and geography.

BY INTEGRATION TYPE

Fan-in WLP

Fan-out WLP

BY PACKAGING TECHNOLOGY

3D TSV WLP

2.5D TSV WLP

WLCSP

Nano WLP

Others (2D TSV WLP and Compliant WLP)

BY BUMPING TECHNOLOGY

Copper Pillar

Solder Bumping

Gold Bumping

Others (Aluminum & Conductive Polymer Bumping)

BY INDUSTRY

Electronics

IT & Telecommunication

Industrial

Automotive

Aerospace & Defense

Healthcare

Others (Media & Entertainment and Non-Conventional Energy Resources)

BY GEOGRAPHY

North America

U.S.

Canada

Mexico

Europe

Germany

UK

France

Netherland

Italy

Rest of Europe

Asia-Pacific

China

India

Japan

South Korea

Taiwan

Rest of Asia-Pacific

LAMEA

Latin America

Middle East

Africa

KEY PLAYERS

Amkor Technology Inc.

Fujitsu Ltd.

Jiangsu Changjiang Electronics Technology Co. Ltd.

Deca Technologies

Qualcomm Inc.

Toshiba Corp.

Tokyo Electron Ltd.

Applied Materials, Inc.

ASML Holding NV

Lam Research Corp.

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FIG. 82 WORLD WAFER LEVEL PACKAGING HEALTHCARE MARKET REVENUE, 2014-2022 (\$MILLION)

FIG. 83 WORLD WAFER LEVEL PACKAGING HEALTHCARE MARKET SHARE, 2014-2022 (%)

FIG. 84 COMPARATIVE REGIONAL MARKET SHARE ANALYSIS OF WORLD WAFER LEVEL PACKAGING OTHERS MARKET, 2015 & 2022 (% SHARE)

FIG. 85 WORLD WAFER LEVEL PACKAGING OTHERS MARKET REVENUE, 2014-2022 (\$MILLION)

FIG. 86 WORLD WAFER LEVEL PACKAGING OTHERS MARKET SHARE, 2014-2022 (%)

FIG. 87 COMPARATIVE WAFER LEVEL PACKAGING MARKET SHARE ANALYSIS, BY GEOGRAPHY (%), 2015 & 2022

FIG. 88 NORTH AMERICA: WORLD WAFER LEVEL PACKAGING MARKET ANALYSIS, 2015 (\$MILLION)

FIG. 89 COMPARATIVE WAFER LEVEL PACKAGING MARKET SHARE ANALYSIS OF NORTH AMERICAN MARKET, BY PACKAGING TECHNOLOGY, 2015 & 2022 (%)

FIG. 90 NORTH AMERICA: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 91 NORTH AMERICA: WAFER LEVEL PACKAGING MARKET, BY PACKAGING TECHNOLOGY, 2014-2022 (%)

FIG. 92 U.S.: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 93 CANADA: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 94 MEXICO: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 95 EUROPE: WORLD WAFER LEVEL PACKAGING MARKET ANALYSIS, 2015 (\$MILLION)

FIG. 96 COMPARATIVE WAFER LEVEL PACKAGING MARKET SHARE ANALYSIS OF EUROPE MARKET, BY PACKAGING TECHNOLOGY, 2015 & 2022 (%)

FIG. 97 EUROPE: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 98 EUROPE: WAFER LEVEL PACKAGING MARKET, BY PACKAGING TECHNOLOGY, 2014-2022 (%)

FIG. 99 GERMANY: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 100 UK: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 101 NETHERLAND: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 102 FRANCE: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 103 ITALY: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 104 REST OF EUROPE: WAFER LEVEL PACKAGING MARKET, 2014-2022 (\$MILLION)

FIG. 105 ASIA-PACIFIC: WORLD WAFER LEVEL PACKAGING MARKET ANALYSIS,

2015 (\$MILLION)

FIG. 106 COMPARATIVE WAFER LEVEL PACKAGING MARKET SHARE ANALYSIS OF ASIA-PACIFIC MARKET, BY PACKAGING TECHNOLOGY, 2015 & 2022 (%)

FIG. 107 ASIA-PACIFIC: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 108 ASIA-PACIFIC: WAFER LEVEL PACKAGING MARKET, BY PACKAGING TECHNOLOGY, 20142022 (%)

FIG. 109 CHINA: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 110 INDIA: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 111 JAPAN: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 112 SOUTH KOREA: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 113 TAIWAN: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 114 REST OF ASIA-PACIFIC: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 115 LAMEA: WORLD WAFER LEVEL PACKAGING MARKET ANALYSIS, 2015 (\$MILLION)

FIG. 116 COMPARATIVE WAFER LEVEL PACKAGING MARKET SHARE ANALYSIS OF LAMEA MARKET, BY PACKAGING TECHNOLOGY, 2015 & 2022 (%)

FIG. 117 LAMEA: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 118 LAMEA: WAFER LEVEL PACKAGING MARKET, BY PACKAGING TECHNOLOGY, 20142022 (%)

FIG. 119 LATIN AMERICA: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 120 MIDDLE EAST: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 121 AFRICA: WAFER LEVEL PACKAGING MARKET, 20142022 (\$MILLION)

FIG. 122 AMKOR TECHNOLOGY: REVENUE, 20132015 (\$MILLION)

FIG. 123 AMKOR TECHNOLOGY: REVENUE BY SEGMENT, 2015 (%)

FIG. 124 AMKOR TECHNOLOGY: REVENUE BY REGION, 2015 (%)

FIG. 125 FUJITSU, REVENUE, 20132015 (\$MILLION)

FIG. 126 FUJITSU, REVENUE, BY SEGMENT (%), 2015

FIG. 127 FUJITSU, REVENUE, BY REGION (%), 2015

FIG. 128 JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY: REVENUE, 20132015 (\$MILLION)

FIG. 129 JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY: REVENUE BY SEGMENT, 2015 (%)

FIG. 130 JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY: REVENUE BY REGION, 2015 (%)

- FIG. 131 DECA TECHNOLOGIES: REVENUE, 20132015 (\$MILLION)
- FIG. 132 DECA TECHNOLOGIES: REVENUE BY SEGMENT, 2015 (%)
- FIG. 133 DECA TECHNOLOGIES: REVENUE BY REGION, 2015 (%)
- FIG. 134 QUALCOMM TECHNOLOGIES: REVENUE, 20132015 (\$MILLION)
- FIG. 135 QUALCOMM TECHNOLOGIES: REVENUE BY SEGMENT, 2015 (%)
- FIG. 136 QUALCOMM TECHNOLOGIES: REVENUE BY REGION, 2015 (%)
- FIG. 137 TOSHIBA CORPORATION: NET SALES, 20132015 (\$MILLION)
- FIG. 138 TOSHIBA CORPORATION: REVENUE BY SEGMENT, 2015 (%)
- FIG. 139 TOSHIBA CORPORATION: REVENUE BY REGION, 2015 (%)
- FIG. 140 TOKYO ELECTRON: REVENUE, 20142016 (\$MILLION)
- FIG. 141 TOKYO ELECTRON: REVENUE BY SEGMENT, 2016 (%)
- FIG. 142 TOKYO ELECTRON: REVENUE BY REGION, 2016 (%)
- FIG. 143 APPLIED MATERIALS: REVENUE, 20132015 (\$MILLION)
- FIG. 144 APPLIED MATERIALS: REVENUE BY SEGMENT, 2015 (%)
- FIG. 145 APPLIED MATERIALS: REVENUE BY REGION, 2015 (%)
- FIG. 146 ASML: REVENUE, 20132015 (\$MILLION)
- FIG. 147 ASML: REVENUE BY SEGMENT, 2015 (%)
- FIG. 148 ASML: REVENUE BY REGION, 2015 (%)
- FIG. 149 LAM RESEARCH: REVENUE, 20142016 (\$MILLION)
- FIG. 150 LAM RESEARCH: REVENUE BY SEGMENT, 2015 (%)
- FIG. 151 LAM RESEARCH: REVENUE BY REGION, 2015 (%)

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